

L Number	Hits	Search Text	DB	Time stamp
-	661	integrated adj circuit and package and metal adj substrate	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 16:18
-	6732954	"12" ans first adj region and second adj region	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 16:40
-	0	((integrated adj circuit and package and metal adj substrate) and substrate near core) and first adj region and second adj region	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 16:40
-	12	(integrated adj circuit and package and metal adj substrate) and substrate near core	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 16:41
-	12	((integrated adj circuit and package and metal adj substrate) and substrate near core) and first and second	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:39
-	2496	(257/691,678).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:37
-	1	((257/691,678).CCLS.) and ((metal adj substrate) with core)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:39
-	1	((257/691,678).CCLS.) and package and ((metal adj substrate) with core)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:39
-	0	((257/691,678).CCLS.) and ((integrated adj circuit and package and metal adj substrate) and substrate near core) and first and second	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:40
-	1	((257/691,678).CCLS.) and package and ((metal adj substrate) with core)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:42
-	40	((257/691,678).CCLS.) and package and (metal adj substrate)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:47
-	2	((257/691,678).CCLS.) and package and (metal adj substrate)) and substrate near core	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 12:43
-	9	((257/691,678).CCLS.) and package and (metal adj substrate) and core	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 13:23
-	2554	(438/106,121).CCLS.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 13:22

-	6	((438/106,121).CCLS.) and package and (metal adj substrate) and core	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 13:23
-	287	package and (metal adj substrate) and core	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 13:23
-	25	package and ((metal adj substrate) with core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 13:26
-	4	package and ((metal adj substrate) near core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 14:57
-	14	((("6317331") or ("6097089") or ("5952716") or ("5900675") or ("6028354") or ("5672911") or ("5741429"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 16:18
-	0	integrated adj circuit and package and metal adj substrate and digital adj ground	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 16:20
-	0	10/033880	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 16:20
-	29207	metal adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 07:58
-	0	(metal adj substrate) and digital and ground	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 07:58
-	386	(metal adj substrate) and digital and ground	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 07:59
-	300	(metal adj substrate) and analog and ground	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 07:59
-	164	((metal adj substrate) and digital and ground) and ((metal adj substrate) and analog and ground)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 07:59
-	522	((metal adj substrate) and digital and ground) or ((metal adj substrate) and analog and ground)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 07:59
-	0	((metal adj substrate) and digital and ground) and ((metal adj substrate) and analog and ground)) and voltage adj rail	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 08:00

-	151	((metal adj substrate) and digital and ground) and ((metal adj substrate) and analog and ground)) and voltage	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 08:00
-	20	((((metal adj substrate) and digital and ground) and ((metal adj substrate) and analog and ground)) and voltage) and digital same ground	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 08:21
-	2	(((((metal adj substrate) and digital and ground) and ((metal adj substrate) and analog and ground)) and voltage) and digital same ground) and packag\$3	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 08:22